Information & Control NA TC Chapter

Meeting Summary and Minutes

SEMICON West

Wednesday, July 10, 2024

9:00-12:00, 1:00-4:00 PM Pacific Time

TC Chapter Announcements

Next TC Chapter Meeting

Wednesday, November 6, 2024

9:00-12:00, 1:00-4:00 PM Pacific Time

Table 1 Meeting Attendees

Italics indicate virtual participants

Co-Chairs: James Moyne (Applied Materials / University of Michigan), Brian Rubow (Cimetrix), Albert Fuchigami (PEER Group)

SEMI Staff: Michelle Sun

Company	*Last*	*First*	*Company*	*Last*	*First*
Advantest	*Taylor*	*John*	Hitachi High-Tech Corporation	Toyoshima	Yuko
Agileo Automation	*Golra*	*Fahad*	Intel Corp.	Bond	Ryan
Agileo Automation	*Til*	*Olivier*	Intel Corporation	*Maloney*	*Chris*
AIS Automation Dresden GmbH	*Mueller*	*Bert*	Intel Corporation	*Viswanath*	*Shuba*
Applied Materials, Inc.	*Moyne*	*James*	PDF Solutions	Huntley	Dave
Arlington Laboratoruy	Judd	Dan	PEER Group Inc.	Fuchigami	Albert
Cimetrix by PDF/SOLUTIONS	Howard	Richard	Samsung	Park	Jae Yong
Cimetrix Incorporated	Tracey	Tami	SCREEN Semiconductor Solutions Co., Ltd.	Nishimura	Takayuki
Cimetrix Incorporated	Rubow	Brian	Self	Infelise	Nicholas
Doople	Kim	Hyungsu	SEMI	Sun	Michelle
EWA-Canada	*Thomas*	*Nicholas*	Tokyo Electron Korea Ltd.	Im	Byoung Min
Ghiselli Consulting	Ghiselli	Jack			

Table 2 Leadership Changes

WG/TF/SC/TC Name	*Previous Leader*	*New Leader*
I&C Co-Chair	Jack Ghiselli [stepped down]	

Table 3 TC Chapter Structure Changes

Previous WG/TF/SC Name	*New WG/TF/SC Name or Status Change*
None	

Table 4 Ballot Results

Document #	*Document Title*	*Committee Action*
7068A	New Standard: Specification for Equipment Data Publication	**Passed**, Ratification Ballot to be Issued
7069A	Revision to Add a New Subordinate Standard: Specification for Common Data for Etch Components to Specification for Equipment Data Publication	**Passed**, Ratification Ballot to be Issued
7175A	Line Item Revision to SEMI E132-0923 Specification for Equipment Client Authentication and Authorization and SEMI E132.2-0923 Specification for Protocol Buffers for Equipment Client Authentication and Authorization (ECA)	
LI-1	Address issues in the primary and subordinate standards and .proto files	**Passed** as balloted
7226	Line Item Revision to SEMI E54.13-1011 - Specification for Sensor/Actuator Network Communications for Ethernet/IP(TM)	
LI-1	Replace Biased Terms	**Failed**
LI-2	Add Mappings for Specific Device Models	**Failed**
LI-3	Updates to References, Trademarks and Other Editorial Changes	**Failed**
7227	Line Item Revision to SEMI E125-0923 Specification for Equipment Self Description (EqSD) and SEMI E125.2-0923 Specification for Protocol Buffers for Equipment Self Description (EqSD)	
LI-1	Address issues in the primary and subordinate standards and .proto files.	**Failed**
7228	Line Item Revision to SEMI E134-0923 Specification for Data Collection Management and SEMI E134.2-0923 Specification for Protocol Buffers of Data Collection Management	
LI-1	Address issues in the primary and subordinate standards and .proto files	**Passed** as balloted
7229	Line Item Revision to SEMI 179-0623 Specification for Protocol Buffers Common Components	
LI-1	Rework Unit Class	**Passed** as balloted
7230	New Standard: Specification for Computing Device Cybersecurity Status Reporting	**Passed**, Ratification Ballot to be Issued
7232	Revision to Add a New Subordinate Standard: Specification for SECS-II Protocol for Computing Device Cybersecurity Status Reporting to Specification for Computing Device Cybersecurity Status Reporting	**Passed**, Ratification Ballot to be Issued
7240	Revision to SEMI E157-0324, Specification for Module Process Tracking	**Failed**
7241	New Standard: Guide for Equipment Adoption Criteria for GEM And GEM-Based Standards	**Failed**
7245	Reapproval of SEMI E151-1211 (Reapproved 0517), Guide for Understanding Data Quality	**Failed**
7246	Reapproval of SEMI E160-1211 (Reapproved 0317), Specification for Communication of Data Quality	**Passed** as balloted

#1 **Passed** ballots and line items will be submitted to the ISC Audit & Review Subcommittee for procedural review.

#2 **Failed** ballots and line items were returned to the originating task forces for re-work and re-balloting or abandoning.

Table 5 Ratification Ballot Results

Document #	*Document Title*	*ISC A&R Action*	*A&R Forms*
None			

Note 1: **Passed** Ratification ballots will be submitted to SEMI publication for final processing.

Note 2: **Failed** Ratification ballots were returned to the originating task forces for re-work and re-balloting or abandoning.

Table 6 Activities Approved by the GCS between meetings of the TC Chapter

#	*Type*	*SC/TF/WG*	*Details*
7240	SNARF	GEM300 TF	Revision to SEMI E157-0324, Specification for Module Process Tracking
7241	SNARF	Advanced Backend Factory Integration (ABFI) TF	New Standard: Guide for Equipment Adoption Criteria for GEM And GEM-Based Standards
7245	SNARF	Process Control System (PCS) TF	Reapproval of SEMI E151-1211 (Reapproved 0517), Guide for Understanding Data Quality
7246	SNARF	PCS TF	Reapproval of SEMI E160-1211 (Reapproved 0317), Specification for Communication of Data Quality

Table 7 Authorized Activities

Listing of all revised or new SNARF(s) approved by the Originating TC Chapter.

#	*Type*	*SC/TF/WG*	*Details*
7268	SNARF	Sensor Bus TF	Line Item Revision of SEMI E54.12, Specification for Sensor/Actuator Network Communications for CC-Link
7269	SNARF	Sensor Bus TF	Line Item Revision of SEMI E54.13, Specification for Sensor/Actuator Network Communications for Ethernet/IP(TM)
7270	SNARF	PCS TF	Line Item Revision to SEMI E151-1211 (Reapproved 0517), Guide for Understanding Data Quality
7271	SNARF	DDA TF	Line Item Revision to SEMI E120-0922 (Reapproved 0823), Specification for the Common Equipment Model (CEM) and SEMI E120.2-0823 Specification for Protocol Buffers for Common Equipment Model (CEM)
7272	SNARF	Diagnostic Data Acquisition (DDA) TF	Line Item Revision to SEMI E132-0923 (Reapproved 0624), Specification for Equipment Client Authentication and Authorization, and E132.2-0923 (Reapproved 0624), Specification for Protocol Buffers for Equipment Client Authentication and Authorization (ECA)
7273	SNARF	DDA TF	Line Item Revision to SEMI E134-0624, Specification for Data Collection Management, and SEMI E134.2-0624, Specification for Protocol Buffers of Data Collection Management
7274	SNARF	DDA TF	Line Item Revision to SEMI E179-0624, Specification for Protocol Buffers Common Components
7275	SNARF	GEM300 TF	Line Item Revision to SEMI E5-0224, Specification for SEMI Equipment Communications Standard 2 Message Content (SECS-II)
7276	SNARF	GEM300 TF	Line Item Revision to SEMI E30-0224, Specification for the Generic Model for Communications and Control of Manufacturing Equipment (GEM)
7277	SNARF	GEM300 TF	Line Item Revision to SEMI E87-0524, Specification for Carrier Management (CMS)
7278	SNARF	GEM300 TF	Line Item Revision to SEMI E90-0624, Specification for Substrate Tracking and SEMI E90.1-0624, Specification for SECS-II Protocol Substrate Tracking
7279	SNARF	GEM300 TF	Line Item Revision to SEMI E172-1023, Specification for SECS Equipment Data Dictionary (SEDD)

#1 SNARFs and TFOFs are available for review on the SEMI Web site at:
http://downloads.semi.org/web/wstdsbal.nsf/TFOFSNARF

Table 8 Authorized Ballots

#	*When*	*TF*	*Details*
6743C	Cycle 7–2024	Graphical User Interfaces (GUI) TF	Revision to SEMI E95-1101, Specification for Human Interface for Semiconductor Manufacturing Equipment
6926A	Cycle 7–2024	Fab & Equipment Computer and Device Security (CDS) TF	New Standard: Specification for Equipment Operator Access Management and Monitoring
7174	Cycle 7–2024	DDA TF	Line Item Revision to SEMI E179-0624, Specification for Protocol Buffers Common Components
7178	Cycle 7–2024	DDA TF	Revision to SEMI E164-0414 (Reapproved 0721), Specification for EDA Common Metadata
7179	Cycle 7–2024	DDA TF	Revision to Add a New Subordinate Standard: Specification for EDA Common Metadata for Generic Model for Communication and Control of Manufacturing Equipment (GEM) to SEMI E164-0414 (Reapproved 0721), Specification for EDA Common Metadata
7180	Cycle 7–2024	DDA TF	Revision to Add a New Subordinate Standard: Specification for EDA Common Metadata for Processing Management to SEMI E164-0414 (Reapproved 0721), Specification for EDA Common Metadata
7181	Cycle 7–2024	DDA TF	Revision to Add a New Subordinate Standard: Specification for EDA Common Metadata for Carrier Management (CMS) to SEMI E164-0414 (0721), Specification for EDA Common Metadata
7182	Cycle 7–2024	DDA TF	Revision to Add a New Subordinate Standard: Specification for EDA Common Metadata for Substrate Tracking to SEMI E164-0414 (0721), Specification for EDA Common Metadata
7183	Cycle 7–2024	DDA TF	Revision to Add a New Subordinate Standard: Specification for EDA Common Metadata for Control Job Management to SEMI E164-0414 (0721), Specification for EDA Common Metadata
7184	Cycle 7–2024	DDA TF	Revision to Add a New Subordinate Standard: Specification for EDA Common Metadata for Equipment Performance Tracker to SEMI E164-0414 (0721), Specification for EDA Common Metadata
7185	Cycle 7–2024	DDA TF	Revision to Add a New Subordinate Standard: Specification for EDA Common Metadata for Time Synchronization and Definition of the TS-Clock Object to SEMI E164-0414 (0721), Specification for EDA Common Metadata
7186	Cycle 7–2024	DDA TF	Revision to Add a New Subordinate Standard: Specification for EDA Common Metadata for Module Process Tracking to SEMI E164-0414 (0721), Specification for EDA Common Metadata
7213	Cycle 7–2024	ABFI TF	Line Item Revision to SEMI E142-1022 - Specification for Substrate Mapping, SEMI E142.1-0921E — Specification for XML Schema for Substrate Mapping, SEMI E142.2-1016 — Specification for SECS II Protocol for Substrate Mapping, SEMI E142.3-1016 — Specification for Web Services for Substrate Mapping, SEMI E142.4-1022 — Specification for SECS II Protocol for Substrate Mapping Using Item Transfer
7227A	Cycle 7–2024	DDA TF	Line Item Revision to SEMI E125-0923 Specification for Equipment Self Description (EqSD) and SEMI E125.2-0923 Specification for Protocol Buffers for Equipment Self Description (EqSD)
7240A	Cycle 7-2024	GEM300 TF	Revision to SEMI E157-0324, Specification for Module Process Tracking
7241A	Cycle 7–2024	ABFI TF	New Standard: Guide for Equipment Adoption Criteria for GEM And GEM-Based Standards

Table 8 Authorized Ballots

#	*When*	*TF*	*Details*
7268	Cycle 7–2024	Sensor Bus TF	Line Item Revision of SEMI E54.12, Specification for Sensor/Actuator Network Communications for CC-Link
7269	Cycle 7–2024	Sensor Bus TF	Line Item Revision of SEMI E54.13, Specification for Sensor/Actuator Network Communications for Ethernet/IP(TM)
7270	Cycle 7–2024	PCS TF	Line Item Revision to SEMI E151-1211 (Reapproved 0517), Guide for Understanding Data Quality
7271	Cycle 7–2024	DDA TF	Line Item Revision to SEMI E120-0922 (Reapproved 0823), Specification for the Common Equipment Model (CEM)
7272	Cycle 7–2024	DDA TF	Line Item Revision to SEMI E132-0923 (Reapproved 0624), Specification for Equipment Client Authentication and Authorization, and E132.2-0923 (Reapproved 0624), Specification for Protocol Buffers for Equipment Client Authentication and Authorization (ECA)
7273	Cycle 7–2024	DDA TF	Line Item Revision to SEMI E134-0624, Specification for Data Collection Management, and SEMI E134.2-0624, Specification for Protocol Buffers of Data Collection Management
7275	Cycle 7–2024	GEM300 TF	Line Item Revision to SEMI E5-0224, Specification for SEMI Equipment Communications Standard 2 Message Content (SECS-II)
7276	Cycle 7–2024	GEM300 TF	Line Item Revision to SEMI E30-0224, Specification for the Generic Model for Communications and Control of Manufacturing Equipment (GEM)
7277	Cycle 7–2024	GEM300 TF	Line Item Revision to SEMI E87-0524, Specification for Carrier Management (CMS)
7278	Cycle 7–2024	GEM300 TF	Line Item Revision to SEMI E90-0624, Specification for Substrate Tracking
7279	Cycle 7–2024	GEM300 TF	Line Item Revision to SEMI E172-1023, Specification for SECS Equipment Data Dictionary (SEDD)
R7068A	Cycle 6–2024	Equipment Data Publication (EDP) TF	New Standard: Specification for Equipment Data Publication
R7069A	Cycle 6–2024	EDP TF	Revision to Add a New Subordinate Standard: Specification for Common Data for Etch Components to Specification for Equipment Data Publication
R7230	Cycle 6–2024	CDS TF	New Standard: Specification for Computing Device Cybersecurity Status Reporting
R7232	Cycle 6–2024	CDS TF	Revision to Add a New Subordinate Standard: Specification for SECS-II Protocol for Computing Device Cybersecurity Status Reporting to Specification for Computing Device Cybersecurity Status Reporting

Table 9 SNARF(s) Granted a One-Year Extension

#	*TF*	*Title*	*Expiration Date*
None			

Table 10 SNARF(s) Cancelled

#	*TF*	*Title*
6845	Sensor Bus TF	Reapproval of SEMI E54-0316, Specification for Sensor/Actuator Network
6848	Sensor Bus TF	Reapproval of SEMI E54.20-0316, Specification for Sensor/Actuator Network Communications for EtherCAT
7226	Sensor Bus TF	Line Item Revision to SEMI E54.13-1011 - Specification for Sensor/Actuator Network Communications for Ethernet/IP(TM)

Table 11 Standard(s) to receive Inactive Status

Standard Designation	*Title*
None	

Table 12 New Action Items

Item #	*Assigned to*	*Details*
None		

Table 13 Previous Meeting Action Items

Item #	*Assigned to*	*Details*
None		

1 Welcome, Reminders, and Introductions

Jack Ghiselli (Ghiselli Consulting) called the meeting to order at 9:03. The meeting reminders on antitrust issues, intellectual property issues and holding meetings with international attendance were reviewed. Attendees introduced themselves.

Attachment: Required Meeting Elements March 2024

2 Review of Previous Meeting Minutes

The TC Chapter reviewed the minutes of the previous meeting.

Motion:	Approve the minutes as written
By / 2nd:	By: Jack Ghiselli / Ghiselli Consulting Second: Dan Judd / Arlington Laboratory
Discussion:	None
Vote:	12-Y 0-N

Attachment: IC-Minutes-March-2024

3 Liaison Reports

3.1 *Information & Control Japan TC Chapter*

Takayuki Nishimura (SCREEN) reported for the Information & Control Japan TC Chapter. Of note:

Meeting Information

- Last meeting
  - Thursday, April 16, 2024, 10:00AM-13:00 [JST]
  - Tokyo Electron office, Tokyo, Japan +Official Virtual TC Chapter Meeting(Hybrid)
- Next meeting
  - Friday July 26th, 2024, 11:00-14:30 [JST]
  - SEMI Japan Office + OVTCCM [Hybrid], April 16, 2024, 10:00AM-13:00 [JST]

Authorized Ballots

- 7173, Line-Item Revision to SEMI E30-0423, SPECIFICATION FOR THE GENERIC MODEL FOR COMMUNICATIONS AND CONTROL OF MANUFACTURING EQUIPMENT (GEM)

Other Topics

- The SEMI SECS GEM / GEM300 tutorial will be available at SEMI University during the first half of 2024. It will be available in Japanese.

Attachment: JA_I&C_Liaison_20240620_v0.1

3.2 *Information & Control Korea TC Chapter*

Michelle Sun (SEMI) reported for the Information & Control Korea TC Chapter. Of note:

- Autonomous Fab Standardization
  - Preliminary talks commenced on February 3, 2024, coinciding with SEMICON Korea 2024.
    - Brainstorming and initial discussions on the necessary preparations for Autonomous Fab standardization took place.
  - Follow up discussion on Mach 15, 2024.
    - Agreement was reached to prioritize near-term items such as PM. However, further discussion is required to achieve consensus and establish a clear vision.

Attachment: Liaison report_InC_KR__Mar2024

3.3 *Information & Control Taiwan TC Chapter*

Michelle Sun (SEMI) reported for the Information & Control Taiwan TC Chapter. Of note:

Meeting Information

- Last meeting
  - April 25th , 2024
  - Hybrid Meeting
- Next meeting
  - August 08th, 2024

Ballot Results

- 6938A, New Standard: Guide for Equipment Edge Data Governance **[Failed]**

Attachment: IC Taiwan Liaison Report_20240425_R1

3.4 *Information & Control China TC Chapter*

Michelle Sun (SEMI) reported for the Information & Control China TC Chapter. Of note:

Last Meeting:

- August 8, 2023

Leadership Changes

- ABFI TF
  - Jia Lu (TongFu Microelectronics) – Stepped Down

Ballot Results

- 7018, Line Item Revision to SEMI E87-0921, Specification for Carrier Management(CMS) and E87.1-0921, Specification for SECS-II Protocol [LI 1-6 passed]

Attachment: China I&C Committee Chapter Liaison Report -v3

3.5 *SEMI Staff Report*

Michelle Sun (SEMI) gave the SEMI Staff Report. Of note:

2024 Calendar of Events

- SEMICON West: July 9-11
- SEMICON Taiwan: September 4-6

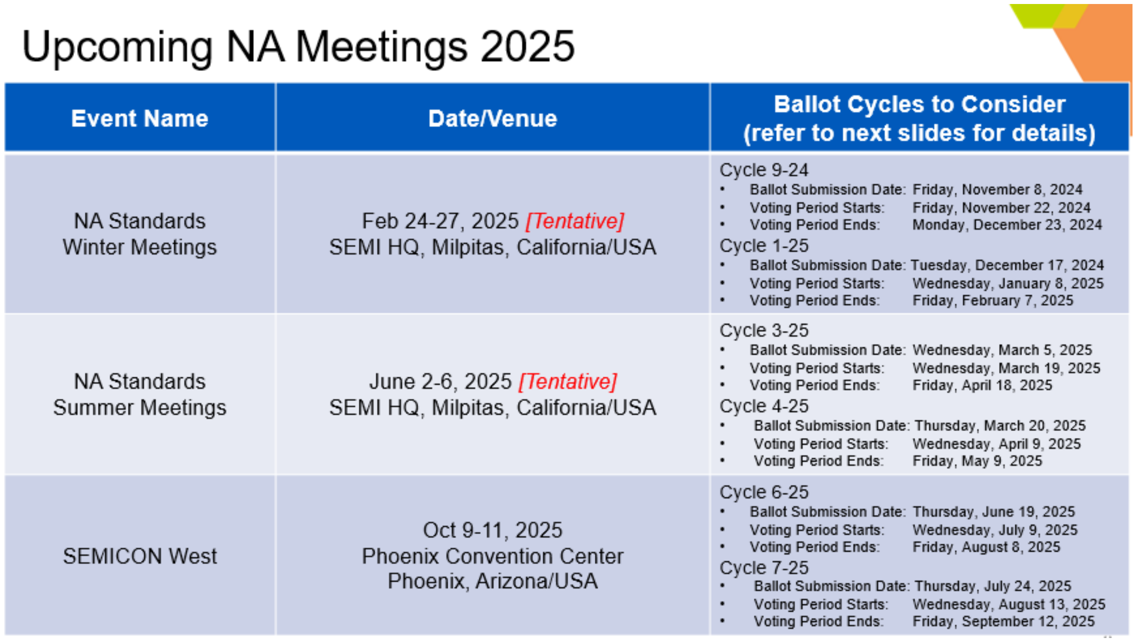
- SEMICON India: September 11-13
- Energy Taiwan: October 2-4
- SEMICON Europa: November 12-15
- SEMICON Japan: December 11-13

SEMICON West 2025-2030

- **2025—October 7-9 | Phoenix Convention Center | Phoenix, AZ**
- 2026—October 13-15 | Moscone Center | San Francisco, CA
- **2027—October 12-14 | Phoenix Convention Center | Phoenix, AZ**
- 2028—October 10-12 | Moscone Center | San Francisco, CA
- **2029—October 9-11 | Phoenix Convention Center | Phoenix, AZ**
- 2030—October 29-31 | Moscone Center | San Francisco, CA

Upcoming NA Meetings 2024

- NA Standards Fall Meetings
  - Nov 4-7, 2024
  - SEMI HQ, Milpitas, CA



Upcoming NA Meetings 2025

Event Name	Date/Venue	Ballot Cycles to Consider (refer to next slides for details)
NA Standards Winter Meetings	Feb 24-27, 2025 *[Tentative]* SEMI HQ, Milpitas, California/USA	Cycle 9-24 • Ballot Submission Date: Friday, November 8, 2024 • Voting Period Starts: Friday, November 22, 2024 • Voting Period Ends: Monday, December 23, 2024 Cycle 1-25 • Ballot Submission Date: Tuesday, December 17, 2024 • Voting Period Starts: Wednesday, January 8, 2025 • Voting Period Ends: Friday, February 7, 2025
NA Standards Summer Meetings	June 2-6, 2025 *[Tentative]* SEMI HQ, Milpitas, California/USA	Cycle 3-25 • Ballot Submission Date: Wednesday, March 5, 2025 • Voting Period Starts: Wednesday, March 19, 2025 • Voting Period Ends: Friday, April 18, 2025 Cycle 4-25 • Ballot Submission Date: Thursday, March 20, 2025 • Voting Period Starts: Wednesday, April 9, 2025 • Voting Period Ends: Friday, May 9, 2025
SEMICON West	Oct 9-11, 2025 Phoenix Convention Center Phoenix, Arizona/USA	Cycle 6-25 • Ballot Submission Date: Thursday, June 19, 2025 • Voting Period Starts: Wednesday, July 9, 2025 • Voting Period Ends: Friday, August 8, 2025 Cycle 7-25 • Ballot Submission Date: Thursday, July 24, 2025 • Voting Period Starts: Wednesday, August 13, 2025 • Voting Period Ends: Friday, September 12, 2025

Critical Dates for SEMI Standards Ballots – 2024 & 2025

2024	Ballot Submission Deadline	Voting Opens	Voting Closes
Cycle 6	July 24	August 7	September 6
Cycle 7	August 27	September 10	October 10
Cycle 8	October 1	October 15	November 14
Cycle 9	November 8	November 22	December 23

2025	Ballot Submission Deadline	Voting Opens	Voting Closes
Cycle 1	Dec 17, 2024	January 8	February 7
Cycle 2	January 23	February 11	March 13
Cycle 3	March 5	March 19	April 18
Cycle 4	March 20	April 9	May 9

SEMI Standards Publications

- Total SEMI Standards in portfolio: 1,088
- Includes 342 Inactive Standards

The Use of Connect@SEMI for TF Management and Document Development Depository

- Refer to PM § 6.4.5 Operation of TFs
  - Task Forces have until 02/20/25 to implement use of Connect@SEMI. (https://connect.semi.org)
  - Once TFs have implemented use of Connect@SEMI, they shall use it to:
    - Maintain the TF member roster up to date.
    - Share the working drafts.
      - The default format for working Draft Document sharing shall be Adobe Acrobat PDF.
    - Distribute the Draft Document at least one week before ballot submission to SEMI.
- All existing TFs have been set up in Connect@SEMI as Communities with the TF leaders assigned community admin and moderator capabilities
- Training materials for TF leaders and members (users) are available at
  - https://www.semi.org/standards
    - Under Standards Developer Resources → Collaboration Tools (scroll to the bottom)

Attachment: IC Staff Report July 2024 v4

4 Ballot Review

NOTE 1: TC Chapter adjudication on ballots reviewed is detailed in the Audits & Review (A&R) Subcommittee Forms for procedural review. The A&R forms are available as attachments to these minutes. The attachment number for each balloted document is provided under each ballot review section below.

4.1 Document #7068A, New Standard: Specification for Equipment Data Publication

Motion:	This Document passed TC Chapter review with technical changes and with or without editorial changes and will be forwarded to the ISC A&R SC for procedural review. A Ratification Ballot will be issued to verify the technical changes.
By / 2nd:	By: Albert Fuchigami / PEER Group Inc.
	Second: Jae Yong Park / Samsung
Discussion:	None
Vote:	16-Y 0-N. Motion passed

Attachment: AR – 7068A

4.2 Document #7069, Revision to Add a New Subordinate Standard: Specification for Common Data for Etch Components to Specification for Equipment Data Publication

Motion:	This Document passed TC Chapter review with technical changes and with or without editorial changes and will be forwarded to the ISC A&R SC for procedural review. A Ratification Ballot will be issued to verify the technical changes.
By / 2nd:	By: Albert Fuchigami / PEER Group Inc.
	Second: Jae Yong Park / Samsung
Discussion:	None
Vote:	17-Y 0-N. Motion passed

Attachment: AR – 7069A

4.3 Document #7175A, Line Item Revision to SEMI E132-0923 Specification for Equipment Client Authentication and Authorization and SEMI E132.2-0923 Specification for Protocol Buffers for Equipment Client Authentication and Authorization (ECA)

Motion:	Line item(s) [1] passed TC Chapter review as balloted and will be forwarded to the ISC A&R SC for procedural review.
By / 2nd:	By: Albert Fuchigami / PEER Group Inc.
	Second: Jack Ghiselli / Ghiselli Consulting
Discussion:	None
Vote:	14-Y 0-N. Motion passed

Attachment: AR – 7175A

4.4 Document #7226, Line Item Revision to SEMI E54.13-1011 - Specification for Sensor/Actuator Network Communications for Ethernet/IP(TM)

Motion:	Line item(s) [1], [2] and [3] failed TC Chapter review and will be returned to the TF for rework
By / 2nd:	By: Dan Judd / Arlington Laboratory
	Second: Jack Ghiselli / Ghiselli Consulting
Discussion:	None
Vote:	16-Y 0-N. Motion passed

4.5 Document #7227, Line Item Revision to SEMI E125-0923 Specification for Equipment Self Description (EqSD) and SEMI E125.2-0923 Specification for Protocol Buffers for Equipment Self Description (EqSD)

Motion:	Line item(s) [1] failed TC Chapter review and will be returned to the TF for rework
By / 2nd:	By: Albert Fuchigami / PEER Group Inc. Second: Hyungsu Kim / Doople
Discussion:	None
Vote:	13-Y 0-N. Motion passed

4.6 Document #7228, Line Item Revision to SEMI E134-0923 Specification for Data Collection Management and SEMI E134.2-0923 Specification for Protocol Buffers of Data Collection Management

Motion:	This Document passed TC Chapter review as balloted and will be forwarded to the ISC A&R SC for procedural review
By / 2nd:	By: Albert Fuchigami / PEER Group Inc. Second: Hyungsu Kim / Doople
Discussion:	None
Vote:	15-Y 0-N. Motion passed

Attachment: AR – 7228

4.7 Document #7229, Line Item Revision to SEMI 179-0623 Specification for Protocol Buffers Common Components

Motion:	This Document passed TC Chapter review as balloted and will be forwarded to the ISC A&R SC for procedural review
By / 2nd:	By: Albert Fuchigami / PEER Group Inc. Second: Jack Ghiselli / Ghiselli Consulting
Discussion:	None
Vote:	15-Y 0-N. Motion passed

Attachment: AR – 7229

4.8 Document #7230, New Standard: Specification for Computing Device Cybersecurity Status Reporting

Motion:	This Document passed TC Chapter review with technical changes and with or without editorial changes and will be forwarded to the ISC A&R SC for procedural review. A Ratification Ballot will be issued to verify the technical changes.
By / 2nd:	By: Albert Fuchigami / PEER Group Inc. Second: Richard Howard / Cimetrix by PDF/SOLUTIONS
Discussion:	None
Vote:	14-Y 0-N. Motion passed

Attachment: AR – 7230

4.9 Document #7232, New Standard: Specification for Computing Device Cybersecurity Status Reporting

Motion: This Document passed TC Chapter review with technical changes and with or without editorial changes and will be forwarded to the ISC A&R SC for procedural review. A Ratification Ballot will be issued to verify the technical changes.

By / 2nd: By: Dan Judd / Arlington Laboratory
Second: Takayuki Nishimura / SCREEN Semiconductor Solutions Co., Ltd.

Discussion: None

Vote: 12-Y 0-N. Motion passed

Attachment: AR – 7232

4.10 Document #7240, Revision to SEMI E157-0324, Specification for Module Process Tracking

Motion: This Document failed TC Chapter review and will be returned to the TF for rework.

By / 2nd: By: Brian Rubow / Cimetrix Incorporated
Second: Takayuki Nishimura / SCREEN Semiconductor Solutions Co., Ltd.

Discussion: None

Vote: 16-Y 0-N. Motion passed

4.11 Document #7241, New Standard: Guide for Equipment Adoption Criteria for GEM And GEM-Based Standards

Motion: This Document failed TC Chapter review and will be returned to the TF for rework.

By / 2nd: By: Brian Rubow / Cimetrix Incorporated
Second: Takayuki Nishimura / SCREEN Semiconductor Solutions Co., Ltd.

Discussion: None

Vote: 16-Y 0-N. Motion passed

4.12 Document #7245, Reapproval of SEMI E151-1211 (Reapproved 0517), Guide for Understanding Data Quality

Motion: This Document failed TC Chapter review and will be returned to the TF for rework.

By / 2nd: By: James Moyne / Applied Materials, Inc.
Second: Dan Judd / Arlington Laboratoruy

Discussion: None

Vote: 14-Y 0-N. Motion passed

4.13 Document #7246, Reapproval of SEMI E160-1211 (Reapproved 0317), Specification for Communication of Data Quality

Motion: This Document passed TC Chapter review as balloted and will be forwarded to the ISC A&R SC for procedural review.

By / 2nd: By: James Moyne / Applied Materials, Inc.
Second: Jack Ghiselli / Ghiselli Consulting

Discussion: None

Vote: 13-Y 0-N. Motion passed

Attachment: AR – 7246

5 Subcommittee and Task Force Reports

5.1 *CDS Task Force*

Ryan Bond (Intel) reported for the CDS Task Force. Of note:

- Ballot Adjudication
  - Ballot 7230: New Standard: Specification for Computing Device Cybersecurity Status Reporting
  - Ballot 7232: Revision to Add a New Subordinate Standard: Specification for SECS-II Protocol for Computing Device Cybersecurity Status Reporting to Specification for Computing Device Cybersecurity Status Reporting
- New Ballots
  - None
- New Informational Ballots
  - None
- Ratification Ballots
  - R7230 – address negative and comments with technical and editorial changes
  - R7232 – address negative and comments with technical changes

Attachment: CDS TF Report 20240709

5.2 *DDA Task Force*

Albert Fuchigami (PEER Group) reported for the DDA Task Force. Of note:

- Ballot Adjudication
  - Passed:
    - Ballot #7175A – Line Item #1 (SEMI E132, E132.2)
    - Ballot #7228 – Line Item #1 (SEMI E134, E134.2)
    - Ballot #7229 – Line Item #1 (SEMI E179)
  - Failed:
    - Doc #7227 Line Item #1 (SEMI E125, E125.2)

Motion:	Approve the following SNARFs: - Line Item Revision to SEMI E132-0924 Specification for Equipment Client Authentication and Authorization and SEMI E132.2-0924 Specification for Protocol Buffers for Equipment Client Authentication and Authorization (ECA) - Line Item Revision to SEMI E134-0924 Specification for Data Collection Management and SEMI E134.2-0924 Specification for Protocol Buffers of Data Collection Management - Line Item Revision to SEMI E120-0922 (Reapproved 0823), Specification for the Common Equipment Model (CEM) - Line Item Revision to SEMI E179-0924, Specification for Protocol Buffers Common Components
By / 2nd:	By: Brian Rubow / Cimetrix Incorporated Second: Albert Fuchigami / PEER Group Inc.
Discussion:	None
Vote:	11-Y 0-N. Motion passed

Attachment: DDA TF Report - SEMICON West 2024_Rev 1.0

5.3 *EDP Task Force*

Jaeyong Park (Samsung) reported for the EDP Task Force. Of note:

- Ballot Adjudication
  - Passed:
    - Ballot #7068A - New Standard: Specification for Equipment Data Publication
    - Ballot #7069A - Revision to Add a New Subordinate Standard: Specification for Common Data for Etch Components to Specification for Equipment Data Publication

Attachment: EDP TF Report - Semicon West - 20240717

5.4 *GUI Task Force*

Tami Tracey (Cimetrix) reported for the GUI Task Force. Of note:

- Reviewed 6743C draft revision 3.1
  - Prior to the meeting, some comments were received from TF members
  - Items discussed in the meeting
- Small Screen Device (SSD) concerns
  - Affordances – Clearer explanation of this concept is needed
  - Visible and non-visible buttons – Motivated to add a new Related Information section for SSD
  - Saliences – How to visualize saliences on non-visible buttons
- Member Comments
  - Proposal that the Command Area could be optional
  - Seems possible under certain conditions
  - Proposal that orientation of Navigation Panel could be vertical instead of mandatory horizontal at bottom of GUI
  - Positive response from TF

Attachment: GUI TF Report - 2024-07-09

5.5 *ABFI Task Force*

Brian Rubow (Cimetrix) reported for the ABFI Task Force. Of note:

- Adjudication
  - 7241 - Move Negative Reason is Related and Technically Persuasive (11/0)
- New ballot discussion
  - 7213 – E142 Revision: Using Position Identifier as an alternative to XY for Transfers
- New SNARF reviews
  - None
- New activity
  - Aligning wafer metrology with E142 device layout

Attachment: NA-ICC-ABFI-TF Report Summer 2024

5.6 *PCS Task Force*

James Moyne (AMAT/University of Michigan) reported for the PCS Task Force. Of note:

- Date and Event
  - # of attendees in person: 6 (including staff)
  - # of attendees remote/online: 2
- TF Leadership & changes (if any): None

- New SNARFs: 1
- Ballot Adjudication:
  - 7245-Reapproval of SEMI E151-1211, Guide for understanding data quality
  - 7246-Reapproval of SEMI E160-1211, Specification for communication of data quality
  - See next few slides
- Old and New business
  - One ballot planned for next meeting (updates to E151)
  - Digital twin activity may lead to support for digital twin standard development starting early in 2025
  - APCSM 2024 is Oct 7-10, 2024 at the Marriott Markham, Toronto, Canada.
    - www.apcsmconference.com
  - Many activities in play related to future PCS TF work
    - NIST AI in semiconductor activity
    - NSF seed funding for Center for Digital Twins in Manufacturing: https://robotics.umich.edu/dtcenter

Motion:	Approve the SNARF for Line Item Revision to SEMI E151-1211, Guide for Understanding Data Quality
By / 2nd:	By: James Moyne / Applied Materials, Inc. Second: Richard Howard / Cimetrix by PDF/SOLUTIONS
Discussion:	None
Vote:	12-Y 0-N. Motion passed

Attachment: PCS-TF-report202407082024

5.7 *GEM 300 Task Force*

Brian Rubow (Cimetrix) reported for the GEM 300 Task Force. Of note:

- Ballot Adjudication:
  - Passed in the Task Force
    - None
  - Ratification Ballot in the Task Force
    - None
  - Failed in the Task Force
    - 7240 E157 Revision ballot
- New Ballots and ballot plans
  - 7240A E157 Revision
  - New SNARF E5 Line-item ballot
  - New SNARF E30 Line-item ballot
  - New SNARF E87 Line-item ballot
  - New SNARF E90 Line-item ballot
  - New SNARF E172 Line-item ballot
- Adjudicated 7240
- Reviewed Multiple SNARFs
- Discussed E87 load port reported information
  - Plan to consider better data reporting related to load ports

Motion: Approve the following SNARFs:

- Line Item Revision to SEMI E5-0224, Specification for SEMI Equipment Communications Standard 2 Message Content (SECS-II)
- Line Item Revision to SEMI E30-0224, Specification for the Generic Model for Communications and Control of Manufacturing Equipment (GEM)
- Line Item Revision to SEMI E87-0524, SEMI E87 - Specification for Carrier Management (CMS)Line Item Revision to SEMI E90
- Line Item Revision to SEMI E172-1023, Specification for SECS Equipment Data Dictionary (SEDD)

By / 2nd:	By: Brian Rubow / Cimetrix Incorporated Second: Albert Fuchigami / PEER Group Inc.
Discussion:	None
Vote:	11-Y 0-N. Motion passed

Attachment: SEMI NA-ICC-GEM300-TF Report Summer 2024

5.8 *ESEC Task Force*

Albert Fuchigami (PEER Group) reported for the ESEC Task Force. Of note:

- Current Activities
  - 7187, Revision to SEMI E167-1213 - Specification for Equipment Energy Saving Mode Communications (EESM) and SEMI E167.1-1213 - Specification for SECS-II Protocol for Equipment Energy Saving Mode Communications
    - Reviewed proposals for a module numbering system

Attachment: SEMI_ESEC_240709

5.9 *Sensor Bus Task Force*

Dan Judd (Arlington Laboratory) reported for the Sensor Bus Task Force. Of note:

- Current Activities
  - Ballot 7226, Line Item Revision to SEMI E54.13-1011, Specification for Sensor/Actuator Network Communications for Ethernet/IP
    - Fail Ballot 7226, and replace with new SNARF to broaden the scope and include addressing consistency and accuracy.
- Proposed SNARFs
  - Line Item Revision to SEMI **E54.13-1011** Specification for Sensor/Actuator Network Communications for Ethernet/IP
    - Scope
      - Cancel and Replace SNARF 7226
      - Add to Scope : check and correct as needed for consistency and accuracy
    - Ballot Target
      - 2024 Cycle 7
  - Line Item Revision to SEMI **E54.12-1019** Specification for Sensor/Actuator Network Communications for CC-Link
    - Scope
      - Revise for RBT
      - Compliance with IP disclaimers and notes per SEMI
      - Check and correct as needed for consistency and accuracy
    - Ballot Target
      - 2024 Cycle 7

Motion:	Approve the SNARF for Line Item Revision to SEMI E54.13-1011 Specification for Sensor/Actuator Network Communications for Ethernet/IP
By / 2nd:	By: Dan Judd / Arlington Laboratory Second: Takayuki Nishimura / SCREEN Semiconductor Solutions Co., Ltd.
Discussion:	None
Vote:	12-Y 0-N. Motion passed

Motion:	Approve the SNARF for Line Item Revision to E54.12-1019 Specification for Sensor/Actuator Network Communications for CC-Link
By / 2nd:	By: Dan Judd / Arlington Laboratory Second: Takayuki Nishimura / SCREEN Semiconductor Solutions Co., Ltd.

Discussion: None
Vote: 12-Y 0-N. Motion passed

Motion: Approve the SNARF for Line Item Revision to E54.12-1019 Specification for Sensor/Actuator Network Communications for CC-Link
By / 2nd: By: Dan Judd / Arlington Laboratory
Second: Takayuki Nishimura / SCREEN Semiconductor Solutions Co., Ltd.
Discussion: None
Vote: 12-Y 0-N. Motion passed

Motion: Approve the SNARF for Line Item Revision to E54.12-1019 Specification for Sensor/Actuator Network Communications for CC-Link
By / 2nd: By: Dan Judd / Arlington Laboratory
Second: Takayuki Nishimura / SCREEN Semiconductor Solutions Co., Ltd.
Discussion: None
Vote: 12-Y 0-N. Motion passed

Motion: Cancel SNARF Document #7226, Line Item Revision to SEMI E54.13-1011 - Specification for Sensor/Actuator Network Communications for Ethernet/IP(TM)
By / 2nd: By: Dan Judd / Arlington Laboratory
Second: Jack Ghiselli / Ghiselli Consulting
Discussion: None
Vote: 15-Y 0-N. Motion passed

Motion: Cancel SNARF Document #6845, Reapproval of SEMI E54-0316, Specification for Sensor/Actuator Network
By / 2nd: By: Dan Judd / Arlington Laboratory
Second: Jack Ghiselli / Ghiselli Consulting
Discussion: None
Vote: 15-Y 0-N. Motion passed

Motion: Cancel SNARF Document #6848, Reapproval of SEMI E54.20-0316, Specification for Sensor/Actuator Network Communications for EtherCAT
By / 2nd: By: Dan Judd / Arlington Laboratory
Second: Jack Ghiselli / Ghiselli Consulting
Discussion: None
Vote: 15-Y 0-N. Motion passed

Attachment: SEMI-NA-Summer2024-ICTC_TF-Report-SensorBus_v1.1

6 Next Meeting and Adjournment

The next meeting is scheduled for Wednesday, November 6, 2024, at SEMI HQ, Milpitas. See http://www.semi.org/standards-events for the current list of events.

Monday, November 4, 2024

- 9:00-10:00 – NA I&C Leadership Meeting
- 10:00-12:00 – ABFI Task Force
- 13:00-14:00 – PCS Task Force

- 14:00-16:00 – GEM300 Task Force
- 16:00-17:30 – EDP Task Force

Tuesday, November 5, 2024

- 8:00-10:00 – GUI Task Force
- 10:00-11:00 – ESEC Task Force
- 11:00-12:00 – Sensor Bus Task Force
- 13:00-16:00 – DDA Task Force
- 16:00-17:30 – CDS Task Force

Wednesday, November 6, 2024

- 9:00-12:00, 13:00-16:00 – I&C NA TC Chapter Meeting

Thursday, November 7, 2024

- 9:00-17:00 – DDA Software Vendor Test

Adjournment: 4:40.

Respectfully submitted by:
Michelle Sun
Coordinator
SEMI North America
Email: msun@semi.org

Minutes tentatively approved by:

<Name> (<Company>), Co-chair	<Date approved>
<Name> (<Company>), Co-chair	<Date approved>

Table 14 Index of Available Attachments[#1]

Title	*Title*
Required Meeting Elements March 2024	IC-Minutes-March-2024
JA_I&C_Liaison_20240620_v0.1	Liaison report_InC_KR__Mar2024
IC Taiwan Liaison Report_20240425_R1	China I&C Committee Chapter Liaison Report -v3
IC Staff Report July 2024 v4	AR – 7068A v2
AR – 7069A v2	AR – 7175A
AR – 7228	AR – 7229
AR – 7230	AR – 7232
AR – 7246	CDS TF Report 20240709
DDA TF Report - SEMICON West 2024_Rev 1.0	EDP TF Report - Semicon West – 20240717
GUI TF Report - 2024-07-09	NA-ICC-ABFI-TF Report Summer 2024
PCS-TF-report202407082024	SEMI NA-ICC-GEM300-TF Report Summer 2024
SEMI_ESEC_240709	SEMI-NA-Summer2024-ICTC_TF-Report-SensorBus_v1.1

#1 Due to file size and delivery issues, attachments must be downloaded separately. A .zip file containing all attachments for these minutes is available at www.semi.org. For additional information or to obtain individual attachments, please contact [SEMI Staff Name] at the contact information above.